PCB Manufacture Capacity

Item	Specification
Material	FR-4, FR1,FR2; CEM-1, CEM-3,Rogers, Teflon,Arlon,Aluminum Base, Copper Base,Ceramic, Crockery, etc.
Remarks	High Tg CCL is Available(Tg>=170°C)
Finish Board Thickness	0.2 mm-6.00mm(8mil-126mil)
Surface Finish	Gold finger(>=0.13um), Immersion Gold(0.025-0075um), Plating Gold(0.025-3.0um), HASL(5-20um), OSP(0.2-0.5um)
Shape	Routing,Punch,V-cut,Chamfer
Surface Treatment	Solder Mask(black, green, white, red, blue, thickness>=12um, Block, BGA) Silkscreen(black, yellow, white) Peel able-mask(red, blue, thickness>=300um)
Minimum Core	0.075mm(3mil)
Copper Thickness	1/2 oz min; 12oz max
Min Trace Width & Line Spacing	0.075mm/0.075mm(3mil/3mil)
Min Hole Diameter for CNC Drilling	0.1mm(4mil)
Min Hole Diameter for Punching	0.6mm(35mil)
Biggest panel size	610mm * 508mm
Hole Position	+/-0.075mm(3mil) CNC Drilling
Conductor Width(W)	+/-0.05mm(2mil) or +/-20% of original
Hole Diameter(H)	PTHL:+/-0.075mm(3mil) Non PTHL:+/-0.05mm(2mil)
Outline Tolerance	+/-0.1mm(4mil) CNC Routing
Warp & Twist	0.70%

Insulation Resistance	10Kohm-20Mohm
Conductivity	<50ohm
Test Voltage	10-300V
Panel Size	110 x 100mm(min) 660 x 600mm(max)
Layer-layer misregistration	4 layers:0.15mm(6mil)max 6 layers:0.25mm(10mil)max
Min spacing between hole edge to circuitry pattern of an inner layer	0.25mm(10mil)
Min spacing between board outline to circuitry pattern of an inner layer	0.25mm(10mil)
Board thickness tolerance	4 layers:+/-0.13mm(5mil)

Flexible PCB product Capacity

FPC Tech Specification

Items	**Capabilities**
Layers	FPC:1 to 6 Layers, Rigid Flex: 2 to 10 Layers
Regular Base Materials	Kapton,Polyimide(PI), Polyester(PET), FR4
Base Copper Thickness	1/3 oz to 8oz
Regular Base Material Thickness	12.5um to 50um(FPC) 0.1mm to 3.2mm(Rigid)
Regular Coverlay Thickness	27um to 50um
Regular Adhesive Thickness	12um to 25um
Blind or Buried Vias	Yes
Impedance Control	Yes
Min.Line Width/Spacing	0.04mm/0.04mm
Surface Finishing	Electroplate Ni/Au(Flash gold/Soft gold/Hard gold), ENIG, HASL, Immersion Tin,OSP
Outline Fabrication	Die cut, laser cut, CNC routing, V-scoring
Hole to edge(Hard tool/Die Cut)	±0.1/±0.2mm

Edge to edge(Hard tool/Die Cut)	±0.05/±0.2mm
Circuit to edge(Hard tool/Die Cut)	±0.07/±0.2mm

PCB Assembly(SMT) Product Capacity

SMT Capacity

SMT Item	Capacity
PCB Max. size	510mm*1200mm(SMT)
Chip component	0201, 0402, 0603, 0805, 1206 package
Min.pin space of IC	0.1mm
Min. space of BGA	0.1mm
Max.precision of IC assembly	±0.01mm
Assembly capacity	≥8 million piots/day
DIP capacity	6 DIP production lines
Assembly testing	Bridge test,AOI test, X-Ray test, ICT(In Circuit Test),FCT(Functional Circuit Test)
FCT(Functional Circuit Test)	Current test, voltage test, high temperature and low temperature test,Drop Impact Test,aging test,water proof test,leakage-proof test and etc.Different test can be done according to your requirement.